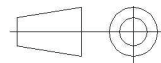
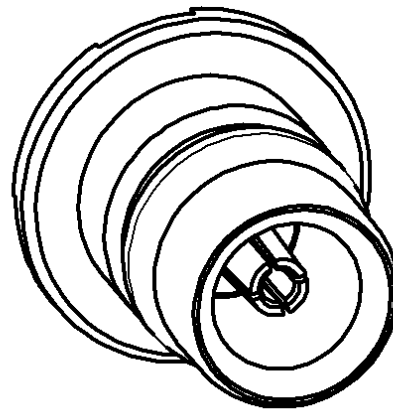
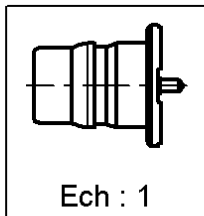
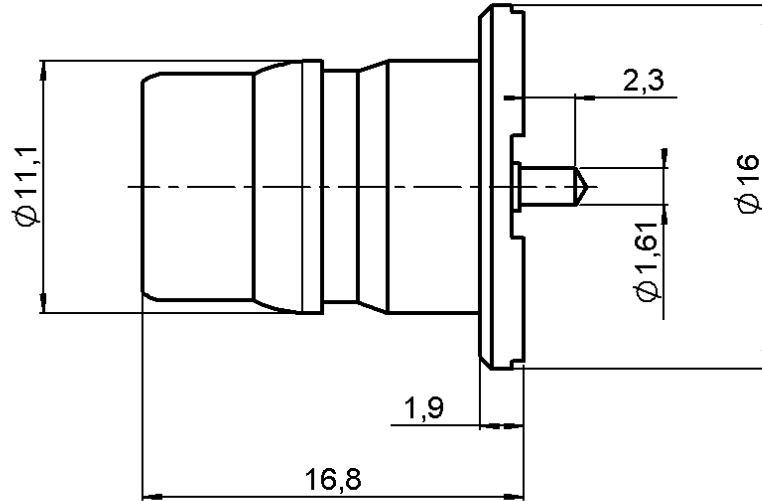


SMT RECEPTACLE

**R164.501.023**

Series : QN



All dimensions are in mm.

COMPONENTS	MATERIALS	PLATINGS (µm)
BODY	BRASS	GBR 2
CENTER CONTACT	BERYLLIUM COPPER	GOLD 1.3 OVER COPPER 2.5
OUTER CONTACT		
INSULATOR	PTFE	
GASKET		
OTHERS PARTS		
-	-	-
-	-	-

Issue : 0420 B

In the effort to improve our products, we reserve the right to make changes judged to be necessary.



**SMT RECEPTACLE**

**R164.501.023**

Series : QN

**PACKAGING**

**SPECIFICATION**

Standard	Unit	Other
<b>50</b>	<b>'W' option</b>	<b>Contact us</b>

**ELECTRICAL CHARACTERISTICS**

**ENVIRONMENTAL**

Impedance		<b>50</b> Ω
Frequency		<b>0-6*</b> GHz
VSWR	<b>**1.05</b> +	<b>0.025</b> x F(GHz) Maxi
Insertion loss		<b>0.048</b> √F(GHz) dB Maxi
RF leakage	- (	<b>***90</b> - F(GHz)) dB Maxi
Voltage rating		<b>1000</b> Veff Maxi
Dielectric withstanding voltage		<b>2000</b> Veff mini
Insulation resistance		<b>5000</b> MΩ mini

Operating temperature	<b>-55/+125°</b> ° C
Hermetic seal	<b>NA</b> Atm.cm3/s
Panel leakage	<b>NA</b>

**OTHERS CHARACTERISTICS**

Assembly instruction

Others :

\*Usable 0-11GHz

\*\*Only for interface

\*\*\* RF Leakage: -80dB min 3<F<6GHz

\*\*\*\*PIM3 : -112dBm (2 x 20W at 1.8GHz)

**MECHANICAL CHARACTERISTICS**

Center contact retention		
Axial force – Mating end	<b>18</b>	N mini
Axial force – Opposite end	<b>18</b>	N mini
Torque	<b>NA</b>	N.cm mini
Recommended torque		
Mating	<b>NA</b>	N.cm
Panel nut	<b>NA</b>	N.cm
Mating life	<b>100</b>	Cycles mini
Weight	<b>9.350</b>	g

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**SMT RECEPTACLE**

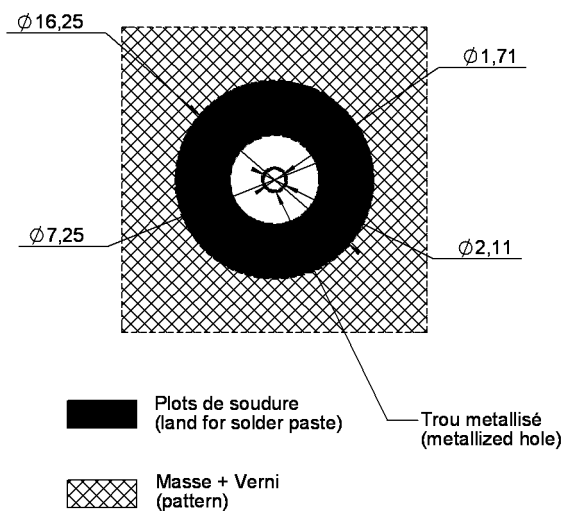
**R164.501.023**

Series : QN

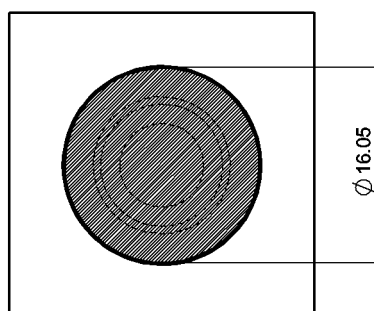
**QN SERIES - INFORMATIONS**

Micro strip line. Signal is on the opposite side .Thickness of PCB : .063(1.6mm)

The material of PCB is the epoxy resin (FR4) (Er = 4.8) . The solder resist should be printed except for the land pattern on the PCB .



**SHADOW OF QN RECEPTACLE FOR VIDEO CAMERA**



Issue : 0420 B

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**SMT RECEPTACLE**

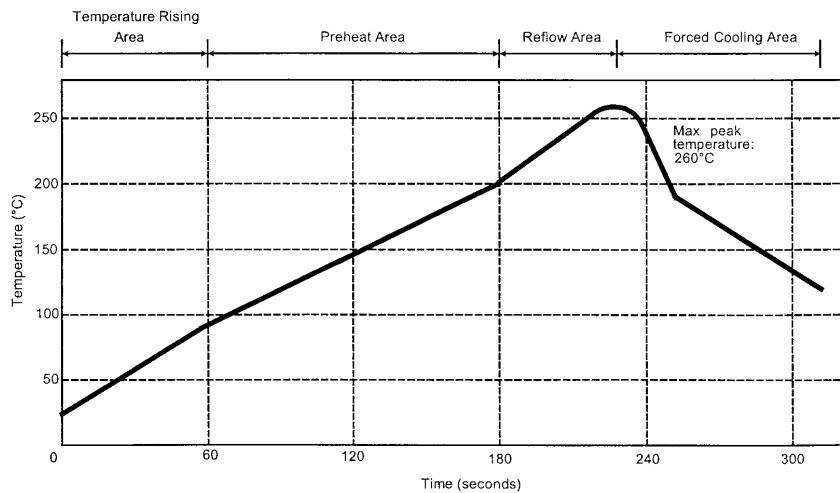
**R164.501.023**

Series : QN

**SOLDER PROCEDURE**

1. Deposit solder paste ‘Sn Ag4 Cu0.5’ on mounting zone by screen printing application. We recommend a low residue flux.  
We advise a thickness of 150 micromm ( 5.850 microinch ). Verify that the edges of the zone are clean.
2. Placement of the receptacle on the mounting zone with an automatic machine of ‘pick and place’ type. Video camera is preferred to check the positioning of the component. Adhesive agents are forbidden on the receptacle.
3. Soldering by infra-red reflow.
4. Cleaning of printed circuit boards.
5. Checking of solder joints and position of the component by visual inspection.

**TEMPERATURE PROFILE**



Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to - 4	°C/sec
Max dwell time above 100°C	420	sec

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